

BUILDING TRUST

SYSTEM DATA SHEET Sikafloor[®] MultiDur ES-24 ECF

Smooth, conductive, low-VOC epoxy flooring system

DESCRIPTION

Sikafloor[®] MultiDur ES-24 ECF is a coloured, electrostatically conductive, low-VOC epoxy flooring system.

USES

Sikafloor[®] MultiDur ES-24 ECF may only be used by experienced professionals.

The System is used in industrial buildings such as:

- Automotive facilities
- Pharmaceutical facilities
- Electronic facilities and data centres
- Manufacturing facilities and workshops
- Logistics facilities and warehouses
- Please note:
- The System may only be used for interior applications.

CHARACTERISTICS / ADVANTAGES

- Electrostatically conductive
- Good resistance to specific chemicals
- Good mechanical resistance
- Low maintenance
- Impermeable to liquids

APPROVALS / STANDARDS

Sikafloor MultiDur ES-24 ECF Fire classification report

SYSTEM INFORMATION

System Structure

Sikafloor® MultiDur ES-24 ECF



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		Layer	Product			
	1.	Primer	Sikafloor®-150 Sikafloor®-151 Sikafloor®-156 Sikafloor®-161 Contact Sika Technical Service for information on choosing the right primer for your project.			
	2.	Conductive primer + Earthing co nection	 n- Sikafloor[®]-220 W Conductive + Sikafloor[®] Conductive Set 			
	3.	Conductive wearing layer	Sikafloor [®] -262 AS N			
	Syste	ORTANT em structure system structure as described in t	he table must not be changed.			
Composition	Еро	Ероху				
Appearance	Smo	oth, semi-gloss finish				
Colour	Cure	Cured system colour Available in various colour shades.				
Nominal Thickness	~1.0	~1.0–1.5 mm				
TECHNICAL INFORMATION						
Tensile Adhesion Strength	≥ 1.5	5 МРа	(EN 1542)			
Reaction to Fire	Clas	s B _{fl} -s1	(EN 13501-1)			
Electrostatic Behaviour	Турі	$\frac{R_{G} < 10^{9} \text{ G}}{\text{cal average resistance}} = \frac{R_{G} < 10^{9} \text{ G}}{R_{G} < 10^{5} $				
	All n (exc lowi	ECF MEASUREMENT CONDITIONS AND SPECIFICATIONSAll measurement values for the system stated in the System Data Sheet(except those referring to proof statements) were measured using the fol-lowing equipment and ambient conditions:Condition or EquipmentSpecification				
			42 (EU) (UK: 8; US: 8,5)			
			90 kg			
		Ambient conditions+23 °C and 50 % r.h.Measuring device for measuring res-Metriso 2000 or 3000 (
		•	comparable			
		ace resistance probe	Carbon Rubber electrode. Weight: 2.50 kg			
	Rub	per pad hardness	Shore A (60 ±10)			
	Measurement results during testing Note: If values are lower or higher than required, carry out additional measurements about 30 cm around the point where the faulty readings are located. If the re-measured values are in accordance with the require- ments, the total area is acceptable. If the requirements cannot be verified, contact Sika Technical Services.					

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APPLICATION INFORMATION

Consumption	Layer	Product	Consumption	
-	Primer	Sikafloor®-150	1–2 × 0.3–0.5 kg/m ²	
		Sikafloor [®] -151	0.	
		Sikafloor [®] -156		
		Sikafloor [®] -161		
	Levelling	Sikafloor [®] -150		
		Sikafloor®-151	Product Data Sheet.	
		Sikafloor [®] -156		
	Constructions and and a	Sikafloor®-161	1 × 0 00 0 10 kg/m²	
	Conductive primer	Sikafloor®-220 W Con- ductive	1 × 0.08–0.10 kg/m²	
	Earthing connection	Sikafloor [®] Conductive Set	1 earthing point per ap- prox. 200–300 m ² , min. <u>2 per room</u>	
	Option 1: Conductive	Sikafloor [®] -262 AS N	Min. 2.25 kg Binder +	
	wearing layer	Filled with Sikafloor [®]	0.25 kg Sikafloor [®] Filler-	
		Filler-1	1.	
			Max. 2.0 kg Binder + 0.5 kg Sikafloor® Filler-1	
	Option 2:Conductive	Sikafloor [®] -262 AS N	Min. 2.25 kg Binder +	
	wearing layer	Filled with quartz sand	0.25 kg quartz sand F34	
		F34	Max. 1.75 kg Binder +	
			0.75 kg quartz sand F34	
	-	ata is theoretical and does i		
	peratures require less Note: Consumption d al material due to sur wastage or any other	ata is theoretical and does in face porosity, surface profil variations. Apply product to n for the specific substrate	e, variations in level, o a test area to calculate	
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BASIS OF PRODUCT DATA

All technical data stated in this Product Data Sheet are based on laboratory tests. Actual measured data may vary due to circumstances beyond our control.

FURTHER INFORMATION

Refer to the following method statements:

- Sika Method Statement Evaluation and preparation of surfaces for flooring systems
- Sika Method Statement Sikafloor[®] mixing and application

ECOLOGY, HEALTH AND SAFETY

User must read the most recent corresponding Safety Data Sheets (SDS) before using any products. The SDS provides information and advice on the safe handling, storage and disposal of chemical products and contains physical, ecological, toxicological and other safety-related data.

APPLICATION INSTRUCTIONS

APPLICATION

INSTALLATION OF EARTHING POINTS Refer to Sika Method Statement: Sika Method Statement — Sikafloor® mixing and application Number of earthing connections per room: Minimum of 2 earthing connections. The optimum number of earthing connections depends on the local conditions and must be specified on drawings or other contract documentation.

LOCAL RESTRICTIONS

Please note that as a result of specific local regulations the performance of this product may vary from country to country. Please consult the local Product Data Sheet for the exact description of the application fields.

LEGAL NOTES

The information, and, in particular, the recommendations relating to the application and end-use of Sika products, are given in good faith based on Sika's current knowledge and experience of the products when properly stored, handled and applied under normal conditions in accordance with Sika's recommendations. In practice, the differences in materials, substrates and actual site conditions are such that no warranty in respect of merchantability or of fitness for a particular purpose, nor any liability arising out of any legal relationship whatsoever, can be inferred either from this information, or from any written recommendations, or from any other advice offered. The user of the product must test the product's suitability for the intended application and purpose. Sika reserves the right to change the properties of its products. The proprietary rights of third parties must be observed. All orders are accepted subject to our current terms of sale and delivery. Users must always refer to the most recent issue of the local Product Data Sheet for the product concerned, copies of which will be supplied on request.

Sika Kimia Sdn. Bhd. Lot 689, Nilai Industrial Estate, 71800 Nilai, Negeri Sembilan D.K. Malaysia Phone: +606-7991762 e-mail: info@my.sika.com Website: www.sika.com.my



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